

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jun YAMAWAKU</td> <td>04/09/2012</td> </tr> <tr> <td>Chishio KOSHIMIZU</td> <td>04/09/2012</td> </tr> <tr> <td>Tatsuo MATSUDO</td> <td>04/09/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jun YAMAWAKU	04/09/2012	Chishio KOSHIMIZU	04/09/2012	Tatsuo MATSUDO	04/09/2012
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Jun YAMAWAKU	04/09/2012								
Chishio KOSHIMIZU	04/09/2012								
Tatsuo MATSUDO	04/09/2012								
RECEIVING PARTY DATA									
Name:	TOKYO ELECTRON LIMITED								
Street Address:	3-1 Akasaka 5-chome, Minato-ku								
City:	Tokyo								
State/Country:	JAPAN								
Postal Code:	107-6325								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13432617</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13432617				
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Application Number:	13432617								
CORRESPONDENCE DATA									
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NAME OF SUBMITTER:	Jaegyo Jang								
Total Attachments: 2 source=Assignment#page1.tif source=Assignment#page2.tif									

OP \$40.00 13432617

ASSIGNMENT

WHEREAS We,

Jun YAMAWAKU of c/o Tokyo Electron Yamanashi Limited, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan,

Chishio KOSHIMIZU of c/o Tokyo Electron Yamanashi Limited, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan and

Tatsuo MATSUDO of c/o Tokyo Electron Yamanashi Limited, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

**COMPONENT IN PROCESSING CHAMBER OF
SUBSTRATE PROCESSING APPARATUS AND METHOD OF
MEASURING TEMPERATURE OF THE COMPONENT**

which claims priority to **Japanese Patent Application No. 2011-069838, filed on March 28, 2011,** and **U.S. Patent Application No. 61/472688, filed on April 7, 2011,** for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **TOKYO ELECTRON LIMITED** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Japan, having a place of business at **Address: 3-1 Akasaka 5-chome, Minato-ku, Tokyo 107-6325, Japan,** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said

Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: Apr. 9. 2012.

Jun Yamawaku.
Jun YAMAWAKU

Date: April 9. 2012

Chishio Koshimizu
Chishio KOSHIMIZU

Date: April 9. 2012

Tatsuo Matsudo
Tatsuo MATSUDO

Date: _____
